

DESCRIPTION

The high power HVV1011-075L device is a high voltage silicon enhancement mode RF transistor designed for L-band pulsed applications operating at 1030 MHz using a 2.4ms pulse burst (32 μ s on/18 μ s off x 48) repeated every 24ms.

FEATURES

- High Power Gain
- Excellent Ruggedness
- 50V Supply Voltage

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DSS}	Drain-Source Voltage	95	V
V _{GS}	Gate-Source Voltage	-10 to 10	V
I _{DSX}	Drain Current	8	A
P _D ²	Power Dissipation	625	W
P _{in}	Input Power	1.7	W
T _s	Storage Temperature	-40 to +150	°C
T _j	Junction Temperature	200	°C

THERMAL CHARACTERISTICS

Symbol	Parameter	Max	Unit
θ_{JC}^1	Thermal Resistance	0.28	°C/W

ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	Typ	Units
V _{BR(DSS)}	Drain-Source Breakdown	V _{GS} =0V, I _D =2mA	102	V
I _{DSS}	Drain Leakage Current	V _{GS} =0V, V _{DS} =50V	<100	μ A
I _{GSS}	Gate Leakage Current	V _{GS} =5V, V _{DS} =0V	<1	μ A
G _p ¹	Power Gain	P _{in} =0.3W, F=1030 MHz	21.5	dB
IRL ¹	Input Return Loss	P _{in} =0.3W, F=1030 MHz	14	dB
P _{OUT}	Power Out	P _{in} =0.3W, F=1030 MHz	75	W
η_D^1	Drain Efficiency	P _{in} =0.3W, F=1030 MHz	45%	%
BD ¹	Burst Droop	P _{in} =0.3W, F=1030 MHz	0.7	dB

¹Under Pulse Conditions: 32 μ s on/18 μ s off x 48, Period = 24ms at V_{DD} = 50V, I_{DQ} = 30mA

²Rated at T_{CASE} = 25°C

PACKAGE



The device utilizes a RoHS compliant metal ceramic flanged package with a ceramic lid. The HV800 package style is qualified for gross leak test – MIL-STD-883, Method 1014.

RUGGEDNESS

The HVV1011-075L device is capable of withstanding an output load mismatch corresponding to a 20:1 VSWR at rated output power over all phase angles and operating voltage across the frequency band of operation.

Symbol	Parameter	Test Condition	Max	Units
LMT ¹	Load Mismatch Tolerance	P _{OUT} = 75W F = 1030 MHz	20:1	VSWR

